

**PROTECTION PRODUCTS - MicroClamp™**
**Description**

The μClamp™ series of TVS arrays are designed to protect sensitive electronics from damage or latch-up due to ESD. It is designed to replace multilayer varistors (MLVs) in portable applications such as cell phones, notebook computers, and PDAs. It features large cross-sectional area junctions for conducting high transient currents. It offers superior electrical characteristics such as lower clamping voltage and no device degradation when compared to MLVs. They offer desirable characteristics for board level protection including fast response time, low operating and clamping voltage, and no device degradation.

The μClamp™1201H is in a 2-pin, RoHS compliant, SOD-523 package. The leads are finished with lead-free matte tin. Each device will protect one line operating at 12 volts. It gives the designer the flexibility to protect single lines in applications where arrays are not practical. They may be used to meet the ESD immunity requirements of IEC 61000-4-2, Level 4 (15kV air, 8kV contact discharge). The combination of small size and high ESD surge capability makes them ideal for use in portable applications such as cellular phones, digital cameras, and MP3 players.

**Features**

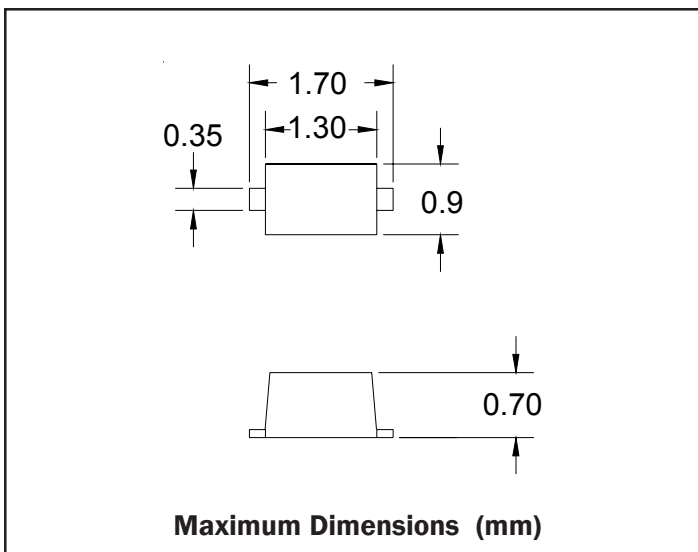
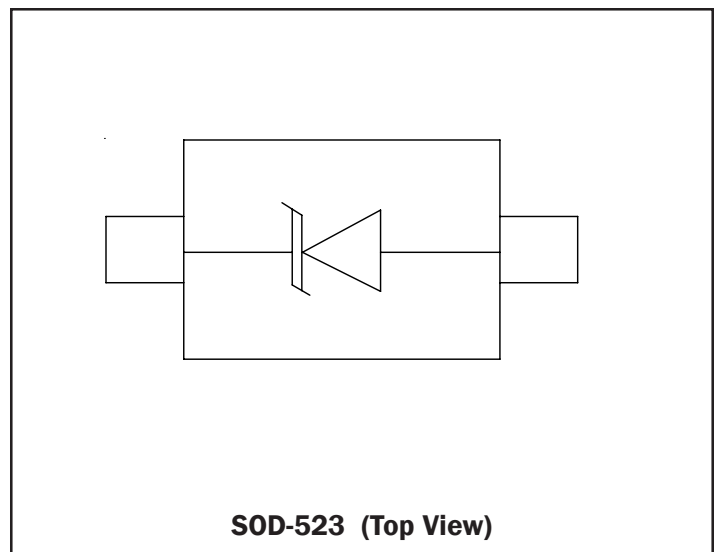
- ◆ Transient protection for data lines to **IEC 61000-4-2 (ESD) ±15kV (air), ±8kV (contact) IEC 61000-4-4 (EFT) 40A (tp = 5/50ns) Cable Discharge Event (CDE)**
- ◆ Ultra-small SOD-523 package (1.7 x 0.9 x 0.7mm)
- ◆ Protects one I/O or power line
- ◆ Low clamping voltage
- ◆ Working voltage: 12V
- ◆ Low leakage current
- ◆ Solid-state silicon-avalanche technology

**Mechanical Characteristics**

- ◆ EIAJ SOD-523 package
- ◆ Molding compound flammability rating: UL 94V-0
- ◆ Marking: Marking code, cathode band
- ◆ Packaging: Tape and Reel per EIA 481
- ◆ Lead Finish: Matte tin
- ◆ RoHS Compliant

**Applications**

- ◆ Cellular Handsets & Accessories
- ◆ Personal Digital Assistants (PDAs)
- ◆ Notebooks & Handhelds
- ◆ Portable Instrumentation
- ◆ Digital Cameras
- ◆ Peripherals
- ◆ MP3 Players

**Dimensions**

**Schematic & PIN Configuration**


**PROTECTION PRODUCTS**
**Absolute Maximum Rating**

Rating	Symbol	Value	Units
Peak Pulse Power ( $t_p = 8/20\mu s$ )	$P_{pk}$	200	Watts
Maximum Peak Pulse Current ( $t_p = 8/20\mu s$ )	$I_{pp}$	8	Amps
ESD per IEC 61000-4-2 (Air) ESD per IEC 61000-4-2 (Contact)	$V_{pp}$	+/- 20 +/- 15	kV
Lead Soldering Temperature	$T_L$	260 (10 sec.)	°C
Operating Temperature	$T_J$	-55 to +125	°C
Storage Temperature	$T_{STG}$	-55 to +150	°C

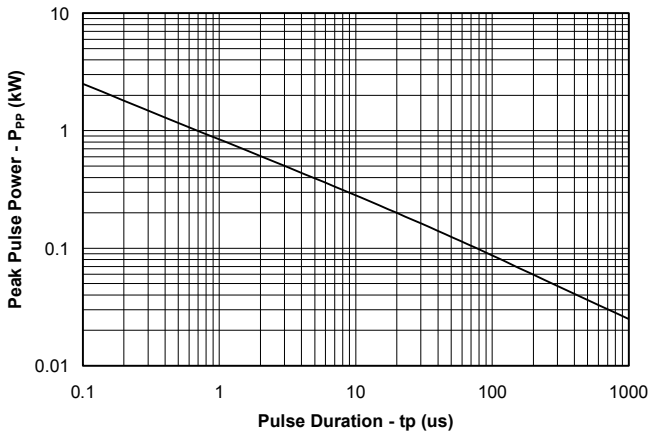
**Electrical Characteristics (T=25°C)**

Parameter	Symbol	Conditions	Minimum	Typical	Maximum	Units
Reverse Stand-Off Voltage	$V_{RWM}$				12	V
Reverse Breakdown Voltage	$V_{BR}$	$I_t = 1mA$	13.3			V
Reverse Leakage Current	$I_R$	$V_{RWM} = 12V, T=25^\circ C$			1	$\mu A$
Forward Voltage	$V_F$	$I_F = 10mA$		0.8		V
Clamping Voltage	$V_C$	$I_{pp} = 1A, t_p = 8/20\mu s$			19	V
Clamping Voltage	$V_C$	$I_{pp} = 8A, t_p = 8/20\mu s$			25	V
Junction Capacitance	$C_j$	$V_R = 0V, f = 1MHz$			60	pF

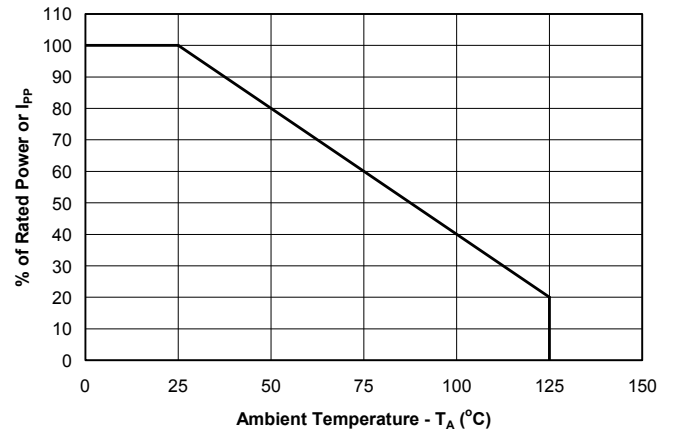
## PROTECTION PRODUCTS

### Typical Characteristics

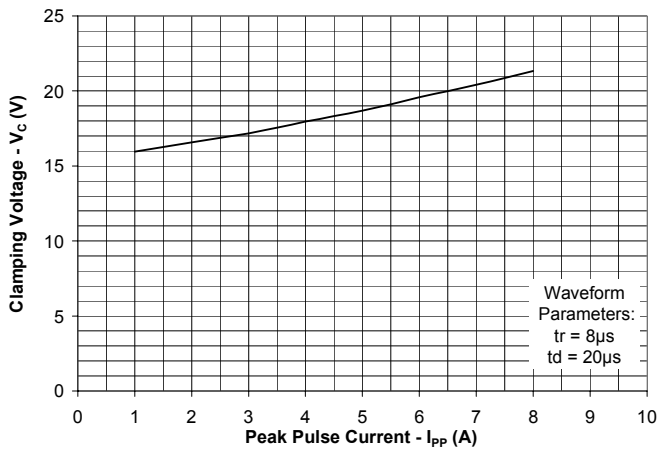
#### Non-Repetitive Peak Pulse Power vs. Pulse Time



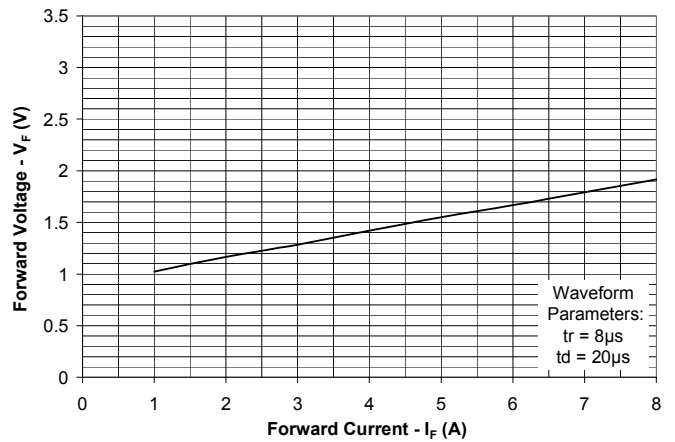
#### Power Derating Curve



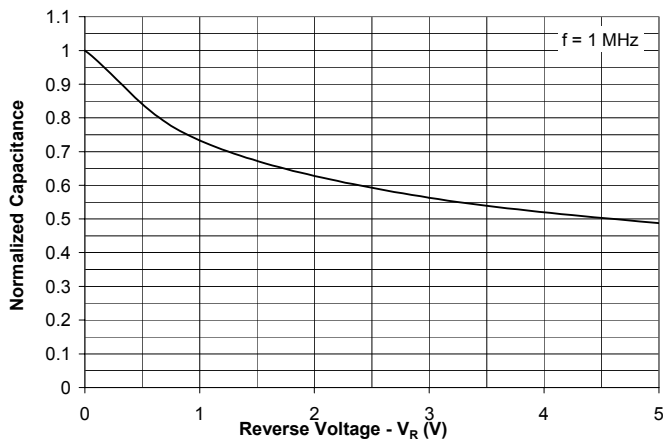
#### Clamping Voltage vs. Peak Pulse Current



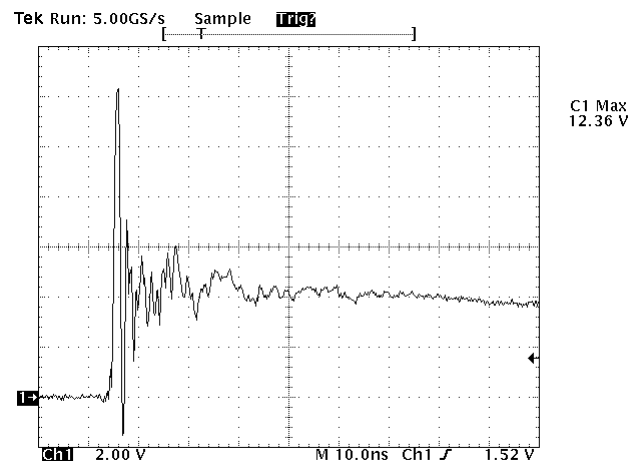
#### Forward Voltage vs. Forward Current



#### Junction Capacitance vs. Reverse Voltage



#### ESD Clamping (8kV Contact per IEC 61000-4-2)



**PROTECTION PRODUCTS****Applications Information****Device Connection Options**

These TVS diodes are designed to protect one data, I/O, or power supply line. The device is unidirectional and may be used on lines where the signal polarity is above ground. The cathode band should be placed towards the line that is to be protected.

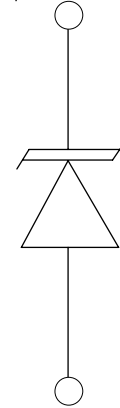
**Circuit Board Layout Recommendations for Suppression of ESD.**

Good circuit board layout is critical for the suppression of ESD induced transients. The following guidelines are recommended:

- Place the TVS near the input terminals or connectors to restrict transient coupling.
- Minimize the path length between the TVS and the protected line.
- Minimize all conductive loops including power and ground loops.
- The ESD transient return path to ground should be kept as short as possible.
- Never run critical signals near board edges.
- Use ground planes whenever possible.

**Matte Tin Lead Finish**

Matte tin has become the industry standard lead-free replacement for SnPb lead finishes. A matte tin finish is composed of 100% tin solder with large grains. Since the solder volume on the leads is small compared to the solder paste volume that is placed on the land pattern of the PCB, the reflow profile will be determined by the requirements of the solder paste. Therefore, these devices are compatible with both lead-free and SnPb assembly techniques. In addition, unlike other lead-free compositions, matte tin does not have any added alloys that can cause degradation of the solder joint.

**Circuit Diagram**

PROTECTION PRODUCTS

Applications Information - Spice Model

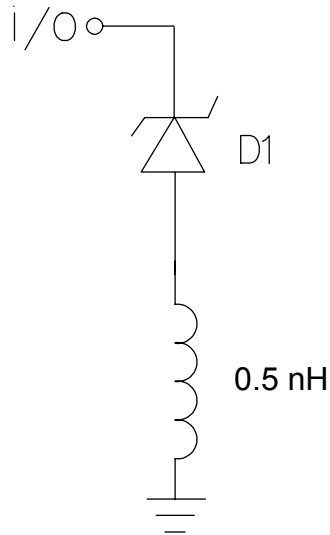


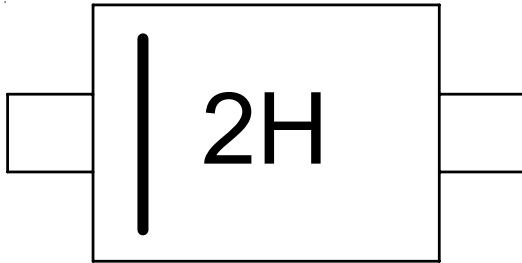
Figure 1 - uClamp1201H Spice Model

Table 1 - uClamp1201H Spice Parameters		
Parameter	Unit	D1 (TVS)
IS	Amp	1.48E-14
BV	Volt	15.33
VJ	Volt	0.723
RS	Ohm	0.772
IBV	Amp	1.0E-3
CJO	Farad	52E-12
TT	sec	2.541E-9
M	--	0.268
N	--	1.1
EG	eV	1.11



## PROTECTION PRODUCTS

### Marking Code



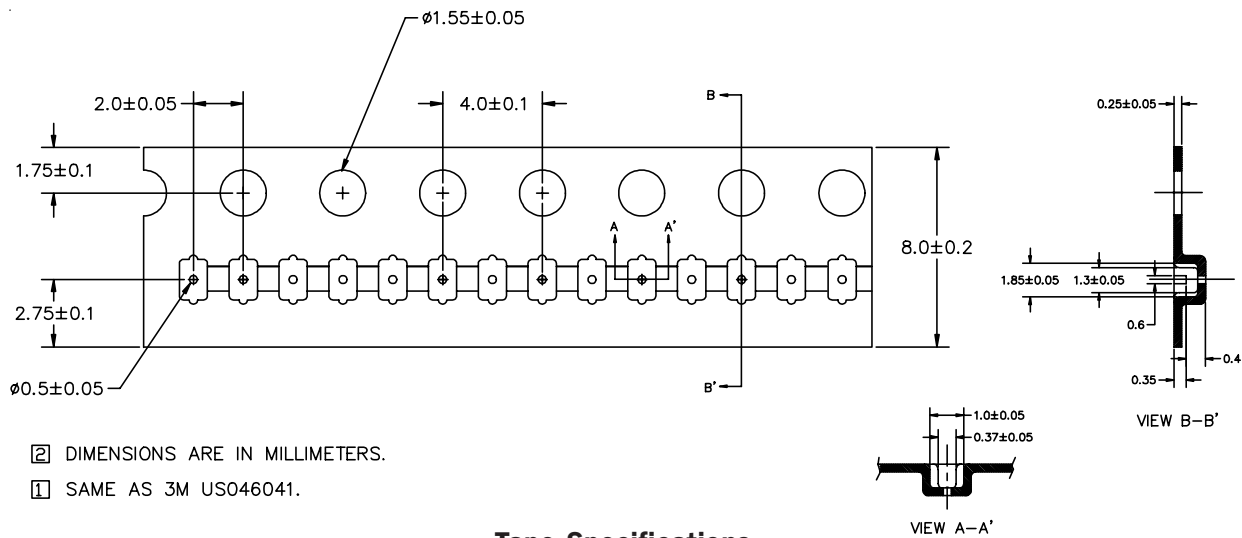
### Ordering Information

Part Number	Working Voltage	Device Marking	Qty per Reel	Reel Size
uClamp1201H.TCT	12V	2H	3,000	7 Inch

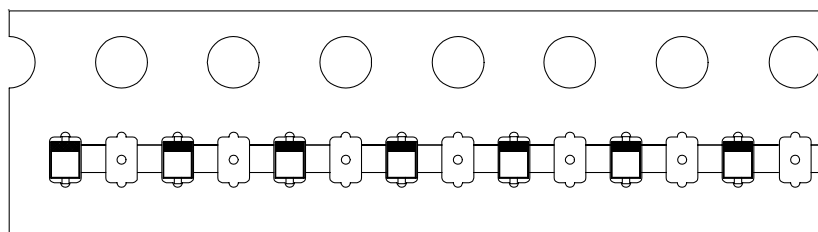
Note: Devices are lead-free

MicroClamp, uClamp and  $\mu$ Clamp are marks of Semtech Corporation

### Tape and Reel Specification



### Tape Specifications



### Device Orientation in Tape

### Contact Information

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